

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/28/2022

Details for "CC430F6147IRGCR"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
CC430F6147IRGCR	NIPDAUAG	Level-3-260C-168 HR	Ext-Mfg	RGC   64	9x9x0.9	159.2

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.422009	97.296057	972961	0.265006	2650
Precious Metals	Gold	7440-57-5	0.000464	0.106977	1070	0.000291	3
Precious Metals	Palladium	7440-05-3	0.011256	2.595121	25951	0.007068	71
Precious Metals	Silver	7440-22-4	0.000008	0.001844	18	0.000005	0
Sub-Total			0.433737	100	1000000	0.27237	2724
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	1.870524	85.500014	855000	1.174618	11746
Thermoplastics	Epoxy	85954-11-6	0.317223	14.499986	145000	0.199204	1992
Sub-Total			2.187747	100	1000000	1.373821	13738
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	42.318038	97.507	975070	26.57411	265741
Copper and Its Alloys	Iron	7439-89-6	0.9765	2.25	22500	0.613205	6132
Copper and Its Alloys	Phosphorus	7723-14-0	0.05425	0.125	1250	0.034067	341
Precious Metals	Silver	7440-22-4	0.012152	0.028	280	0.007631	76
Zinc and Its Alloys	Zinc	7440-66-6	0.03906	0.09	900	0.024528	245
Sub-Total			43.4	100	1000000	27.253541	272535
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.4865	97.3	973000	0.305503	3055
Precious Metals	Gold	7440-57-5	0.0015	0.3	3000	0.000942	9
Precious Metals	Palladium	7440-05-3	0.0105	2.1	21000	0.006594	66
Precious Metals	Silver	7440-22-4	0.0015	0.3	3000	0.000942	9
Sub-Total			0.5	100	1000000	0.313981	3140
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	94.780932	90.5	905000	59.518801	595188
Other Plastics and Rubber	Carbon Black	1333-86-4	0.523652	0.5	5000	0.328833	3288
Thermoplastics	Epoxy	85954-11-6	9.425728	9	90000	5.919997	59190
Sub-Total			104.730312	100	1000000	65.766632	657666
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	7.993568	100	1000000	5.019655	50197
Sub-Total			7.993568	100	1000000	5.019655	50197
<b>Total</b>			159.245364			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.